

## Appendix

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## LOW JITTER INPUT BUFFER WITH SMALL INPUT SIGNAL SWING

### Background of the Invention

#### Field of the Invention

5 [0001] The present invention generally relates to an interface circuit, and particularly to a low jitter input buffer.

#### Description of Related Art

[0002] Major design efforts have been directed at circuit design techniques involving input circuits for memory devices. A number of solutions have 10 been proposed.

[0003] U.S. Patent 5,978,310 (Bae et al) describes an input buffer for a DRAM memory device, which removes noise from the row address strobe. The device has a data output enable, which can be delayed for a predetermined time, and which also produces a control signal for the 15 output. There is also a buffer output for producing the noise free input according to the control signal.

[0004] U.S. Patent 6,002,618 (Komarek et al) discloses an NMOS input receiver circuit for a read only memory. It includes a feedback loop to control hysteresis. There is a second stage and an additional output for the receiver. Switching noise from inside the memory is isolated and cannot be fed back into the receiver circuit to affect the TTL voltage levels.

5 Wide, long FET sizes are used to minimize manufacture variations in the receiver switching levels.

[0005] What is still needed is a mechanism by which an input buffer works in the presence of ground noise, specifically how capacitance can be used to reduce such noise for a memory input circuit.

### **Summary of the Invention**

[0006] It is therefore an object of the present invention to provide an efficient circuit design technique for an input buffer receiver for a particular memory device[[,]] that works to filter ground noise. It is a further object of the invention to provide a means for reducing jitter in an input buffer. This is achieved by attaching a large capacitance to the PMOS-bias node of the input buffer receiver.

[0007] These and other objects are achieved by an input buffer receiver comprising: a buffer input portion for receiving an input signal ~~SIGNAL\_IN~~;

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a large capacitor capacitance C<sub>HC</sub> between a PMOS bias node and a V<sub>SS</sub> source lower supply voltage V<sub>SS</sub>, and a buffer output portion for producing an output signal SIGNAL\_OUT1. Furthermore, in the input buffer receiver, the VB11 gate biasing voltage of the bias node of transistors P11 and P12 is charge coupled to the V<sub>SS</sub> lower voltage source voltage. This results in a quicker response time for the output signal SIGNAL\_OUT1.

#### Brief Description of the Drawings

[0008] The foregoing and other objects, aspects, and advantages will be

10 better understood from the following detailed description of a preferred embodiment of the invention, with reference to the drawings, in which:

[0009] FIG. 1 is a diagram of an input buffer receiver according to the prior art.

[0010] FIG. 2 is a diagram of an input buffer receiver according to the present invention.

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[0011] FIGS.3A-B show the timing diagrams of the input buffer receiver of the present invention and the definitions of JITTER\_RISE and JITTER\_FALL.

[0012] FIGS. 4A-B illustrate the workings of capacitance-capacitor CHC to reduce JITTER\_RISE and JITTER\_FALL.

### Detailed Description of the Invention

[0013] One embodiment of the present invention is provided below with reference to the accompanying diagrams.

[0014] Referring to FIG. 1, the input buffer receiver of the prior art includes a buffer input portion 100 for receiving an input signal SIGNAL\_IN and a buffer output portion 200 for producing an output signal SIGNAL\_OUT.

[0015] The buffer input portion 100 is comprised of: NMOS transistors N1 and N2, where a lower supply voltage VSS is applied to the source nodes of NMOS transistors N1 and N2, and PMOS transistors P1 and P2, where an upper voltage supply VDD is applied to the source nodes. The gate nodes of transistors P1 and P2 and the drains of transistors N1 and P1 are connected together to form the biasing node b1. The biasing voltage VB1 is developed at the biasing node b1 as a result of the configuration of transistors P1 and P2. A parasitic capacitor Cp is present from the biasing node b1 to the ground reference node. and a signal VB1 is applied to the gate nodes of P1 and P2. In the prior art, a reference voltage VREF is applied to the gate of transistor N1, input signal SIGNAL\_IN is applied to

the gate of transistor N2, and VB1 is applied to the drain of N1 and the drain of P1, as well as the PMOS bias node of P1 and P2. Input signal SIGNAL\_IN is a low swing signal coming from off chip. The buffer output portion 200 is comprised of a common node for the drain of transistor N2 and drain of transistor P2, which serves as input to inverter I1. The output of inverter I1 is the output signal output SIGNAL\_OUT.

5 [0016] The ground noise (VSS noise), as described above, is developed between the lower supply voltage VSS and the ground reference voltage.  
The magnitude of the VSS noise affects the delay timing from the input 10 signal SIGNAL\_IN to the output signal SIGNAL\_OUT. The variation in the delay causes jitter in the rise and fall delays of the buffer and thus slower response times.

10 [0017] Referring to FIG. 2, the proposed invention is comprised of a similar buffer input portion 101 and a similar buffer output portion 201. The buffer input portion 101 is comprised of: NMOS transistors N11 and N12, where 15 a the lower supply voltage VSS is applied to the source nodes of N11 and N12, and PMOS transistors P11 and P12, where an upper supply voltage VDD is applied to the source nodes. The gate nodes of transistors P11 and P12 and the the drains of transistors N11 and P11 are connected  
20 together to form the biasing node b11. The biasing voltage VB11 is

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developed at the biasing node b11 as a result of the configuration of transistors P11 and P12. A parasitic capacitor Cp is present from the biasing node b11 to the ground reference node. A signal VB11 is applied to the gate nodes of P11 and P12. A reference supply voltage VREF is applied to the gate of transistor N11, input signal SIGNAL\_IN is applied to the gate of N12, and VB11 is applied to the drain of N11 and the drain of P11. In the present invention, a large capacitance capacitor CHC is attached between the PMOS bias node VB11 b11 and the lower supply source-voltage VSS. The buffer output portion 201 is comprised of a common node for the drain of transistor N12 and the drain of transistor P12, which serves as input to inverter I11. The output of inverter I11 is the output signal SIGNAL\_OUT1 of the invention.

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[0018] The large capacitance CHC is in series with the parasitic capacitor Cp capacitance of the input buffer receiver devices transistors N11, P11, and P12. The large capacitor CHC, as connected, is designed to have an extremely large capacitance relative to the parasitic capacitor Cp such that the bias voltage VB11 essentially follows the voltage changes in the lower supply voltage VSS preventing the effects of the VSS noise. This coupling ratio is determined by the formula:

$$\frac{CHC}{Cp + CHC} \approx 1$$

where:

CHC is the capacitance value of the large capacitor

CHC.

5 Cp is the capacitance value of the parasitic capacitor

Cp.

[0019] Because of its large coupling ratio (very close to 1), the capacitor CHC essentially charge couples the biasing voltage VB11 gate voltage of the PMOS bias node b11, to the VSS source lower supply voltage VSS, of devices N11 and N12. This forces the transistors N11 and N12 to activate and deactivate essentially simultaneously, allowing for a quicker response time on output signal SIGNAL\_OUT1.

[0020] FIGS. 3A-B are diagrams of timed operation showing the input signal SIGNAL\_IN, the source lower supply voltage VSS, and the output signal SIGNAL\_OUT1 of the proposed invention. It should be noted that the input signal SIGNAL\_IN is defined as VIH=VREF+350mv and VIL=VREF-350mv, and VSS is 200mv. The output signal SIGNAL\_OUT1 is defined by the delayed signal delay times DELTA1 or DELTA2, when

input signal SIGNAL\_IN rises, and the delay times DELTA3 or DELTA4, when the input signal SIGNAL\_IN falls. The delay time DELTA1 is defined as the delay from the rising edge of input signal SIGNAL\_IN to the rising edge of output signal SIGNAL\_OUT, when VSS=200mv. It is the delay on output signal SIGNAL\_OUT1 when transistor N12 sees VSS noise and turns on weakly. The delay time DELTA2 is defined as the delay from the rising edge of input signal SIGNAL\_IN to the rising edge of output signal SIGNAL\_OUT1, when VSS=0v. It is the delay on-of the output signal SIGNAL\_OUT1 when transistor N12 does not see VSS noise and turns on strongly. The delay time DELTA3 is defined as the delay from the falling edge of input signal SIGNAL\_IN to the falling edge of output signal SIGNAL\_OUT1, when VSS=0v. It is the delay on-of the input signal SIGNAL\_OUT1 when transistor N12 does not see VSS noise and turns off weakly. DELTA4 is defined as the delay from the falling edge of input signal SIGNAL\_IN to the falling edge of output signal SIGNAL\_OUT1, when VSS=200mv. It is the delay seen on output signal SIGNAL\_OUT1 when transistor N12 sees VSS noise and turns off strongly. By definition, the delay times DELTA2 and DELTA4 are smaller than the delay times DELTA1 and DELTA3. The rise time jitter JITTER\_RISE is the difference between the delay times DELTA1 and DELTA2 when the input signal SIGNAL\_IN rises and the fall time jitter JITTER\_FALL is the difference

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between the delay times DELTA3 and DELTA4 when input signal SIGNAL\_IN falls. The intent of the invention capacitance large capacitor CHC is to reduce rise time jitter JITTER\_RISE and fall time jitter JITTER\_FALL by primarily having devices transistors P12 and N12, activate, in the presence or absence of ground noise, almost simultaneously.

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[0021] FIGS. 4A-B illustrate the workings of large capacitor CHC. In Fig. 4a, the large capacitor is shown in series with the parasitic capacitor Cp. The large capacitance coupling ratio of the large capacitor CHC versus the capacitance of the parasitic capacitor Cp creates a charge coupling couples of the PMOS bias node, VB11\_b11, of the input buffer receiver, to the VSS-source lower supply voltage VSS, of the input buffer receiver. This results in a quicker response time for a input signal SIGNAL\_OUT1.

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[0022] While the invention has been described in terms of the preferred embodiments, those skilled in the art will recognize that various changes in form and details may be made without departing from the spirit and scope of the invention. The present invention covers modifications that fall within the range of the appended claims and their equivalents.

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[0023] While this invention has been particularly shown and described with reference to the preferred embodiments thereof, it will be understood by

those skilled in the art that various changes in form and details may be made without departing from the spirit and scope of the invention.

[0024]      What is claimed is:

1. 1. (Currently Amended) An input buffer receiver comprising:
  2. a buffer input portion for receiving an input signal SIGNAL\_IN, said buffer input portion comprising a bias node;
  4. a large capacitor capacitance between a PMOS the bias node and a VSS source lower supply voltage said large capacitor providing a coupling ratio between said large capacitor and a parasitic capacitor coupled between said bias node and a ground reference point approaching a unity value such that a biasing voltage at said biasing node follows said lower supply voltage to minimize effects of a ground noise signal between the lower supply voltage and the ground reference point; and
  12. a buffer output portion in communication with the buffer input portion for producing an output signal SIGNAL\_OUT1.
1. 2. (Currently Amended) The input buffer receiver of claim 1, wherein the buffer input portion which receives an the input signal SIGNAL\_IN further comprises:
  4. a first transistor of a first conductivity type N11 having a source node to which a VSS source the lower supply voltage is applied,

6           a gate node to which a reference voltage  $V_{REF}$  is applied, and  
7           a drain node at which the biasing voltage is developed to which

8           a signal  $VB_{11}$  is applied;

9           a second transistor of a second conductivity type  $P_{11}$  having a  
10          drain node which is connected to the drain node of the first  
11          transistor  $N_{11}$ , and a gate node at which the biasing voltage is  
12          developed to which a signal  $VB_{11}$  is applied, and a source node  
13          to which an upper supply voltage source  $V_{DD}$  is applied;

14          a third transistor of the second conductivity type  $P_{12}$  having a drain  
15          node which is connected to the drain of a fourth transistor  $N_{12}$ ,  
16          a gate node at which the biasing voltage is developed to which  
17          a signal  $VB_{11}$  is applied, and a source node to which an the  
18          upper supply voltage source  $V_{DD}$  is applied;

19          a fourth transistor of the first conductivity type  $N_{12}$  having a source  
20          node to which a  $V_{SS}$  source lower supply voltage is applied, a  
21          gate node to which an input signal  $SIGNAL\_IN$  is applied  
22          externally, and a drain node which is the an input to the buffer  
23          output portion.

- 1       3. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              first and fourth transistors, N11 and N12, are NMOS transistors, and the
- 3              second and third transistors, P11 and P12, are PMOS transistors.
- 1       4. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              large capacitor capacitance is connected between the sources of the first
- 3              and fourth transistors, N11 and N12, of the buffer input portion and the
- 4              gate of the second transistor P11 of the buffer input portion.
- 1       5. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              gate of the second transistor P11 is connected to its drain.
- 1       6. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              gate of the second transistor P11 is connected to the drain of the first
- 3              transistor N11.
- 1       7. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              gate of the second transistor P11 is connected to the gate of the third
- 3              transistor P12.
- 1       8. (Currently Amended) The input buffer receiver of claim 2-4, wherein the
- 2              buffer output portion which produces an output signal SIGNAL\_OUT1

3                   comprises: a first inverter I11-connected to the drain of the third transistor  
4                   P12-and the drain of the fourth transistor-N12;

1       9. (Currently Amended) The input buffer receiver of claim 2-4, wherein P12  
2                   and N12 the third transistor and the fourth transistor activate almost  
3                   simultaneously to provide an efficient circuit design technique for filtering  
4                   minimize the effects of ground noise on a delay jitter factor of said input  
5                   buffer.

1       10. (Currently Amended) The input buffer receiver of claim 1, involving a large  
2                   capacitance coupling ratio, which wherein the large capacitor charge  
3                   couples the PMOS-bias node of the input buffer receiver to the VSS  
4                   source lower supply voltage of the input buffer receiver and wherein a  
5                   capacitance value of the large capacitor is selected by the formula:-

$$\frac{CHC}{Cp + CHC} \approx 1$$

7                   where:

8                   CHC is the capacitance value of the large capacitor,  
9                   and

10                  Cp is the capacitance value of the parasitic capacitor.

1       11. (Currently Amended) The input buffer receiver of claim 1, ~~involving a~~  
2                   wherein the capacitance value of the large capacitor relative to said  
3                   parasitic capacitor capacitance coupling ratio, which results in a quicker  
4                   response time for the output signal-a SIGNAL\_OUT1.

1       12. (New) An integrated circuit formed on a substrate comprising:  
2                   an input buffer receiver for receiving an input signal and connected  
3                   to said distribution network, said input buffer comprising:  
4                   a buffer input portion for receiving the input signal, said  
5                   buffer input portion comprising a bias node;  
6                   a large capacitor between the bias node and a lower  
7                   supply voltage, said large capacitor providing a  
8                   coupling ratio between said large capacitor and a  
9                   parasitic capacitor coupled between said bias node  
10                  and a ground reference point approaching a unity  
11                  value such that a biasing voltage at said biasing node  
12                  follows said lower supply voltage to minimize effects  
13                  of a ground noise signal between the lower supply  
14                  voltage and the ground reference point ; and

15 a buffer output portion in communication with the buffer  
16 input portion for producing an output signal.

1 13. (New) The integrated circuit of claim 12, wherein the buffer input portion of  
2 the input buffer receiver further comprises:

3           a first transistor of a first conductivity type having a source node to  
4           which the lower supply voltage is applied, a gate node to which  
5           a reference voltage is applied, and a drain node at which the  
6           biasing voltage is developed ;

7                   a second transistor of a second conductivity type having a drain  
8                   node which is connected to the drain node of the first transistor,  
9                   and a gate node at which the biasing voltage is developed, and  
10                  a source node to which an upper supply voltage source is  
11                  applied;

12 a third transistor of the second conductivity type having a drain  
13 node which is connected to the drain of a fourth transistor, a  
14 gate node at which the biasing voltage is developed, and a  
15 source node to which the upper supply voltage source is  
16 applied;

17           a fourth transistor of the first conductivity type having a source node  
18           to which lower supply voltage is applied, a gate node to which  
19           an input signal is applied externally, and a drain node which is  
20           an input to the buffer output portion.

1     14. (New) The integrated circuit of claim 13, wherein the first and fourth  
2       transistors are NMOS transistors, and the second and third transistors are  
3       PMOS transistors.

1     15. (New) The integrated circuit of claim 13, wherein the large capacitor is  
2       connected between the sources of the first and fourth transistors of the  
3       buffer input portion and the gate of the second transistor of the buffer input  
4       portion.

1     16. (New) The integrated circuit of claim 13, wherein the gate of the second  
2       transistor is connected to its drain.

1     17. (New) The integrated circuit of claim 13, wherein the gate of the second  
2       transistor is connected to the drain of the first transistor.

1     18. (New) The integrated circuit of claim 13, wherein the gate of the second  
2       transistor is connected to the gate of the third transistor.

1    19. (New) The integrated circuit of claim 13, wherein the buffer output portion  
2       which produces output signal comprises: a first inverter connected to the  
3       drain of the third transistor and the drain of the fourth transistor;

1    20. (New) The integrated circuit of claim 13, wherein the third transistor and  
2       the fourth transistor activate almost simultaneously to minimize the effects  
3       of ground noise on a delay jitter factor of said input buffer.

1    21. (New) The integrated circuit of claim 12, wherein the large capacitor  
2       charge couples the bias node of the input buffer receiver to the lower  
3       supply voltage of the input buffer receiver and wherein a capacitance  
4       value of the large capacitor is selected by the formula:

$$\frac{CHC}{Cp + CHC} \approx 1$$

6                      where:

7                      CHC is the capacitance value of the large capacitor,

8                      and

9                      Cp is the capacitance value of the parasitic capacitor.

1    22. (New) The integrated circuit of claim 12, wherein the capacitance value of  
2       the large capacitor relative to said parasitic capacitor results in a quicker  
3       response time for the output signal.

1    23. (New) A method for minimizing effects of ground noise on an input buffer  
2       receiver comprising the steps of:  
3               forming a buffer input portion for receiving an input signal on a  
4               substrate;  
5               forming a bias node within said buffer input portion;  
6               connecting said a lower supply voltage to said buffer input portion;  
7               forming a large capacitor between the bias node and the lower  
8               supply voltage said large capacitor providing a coupling ratio  
9               between said large capacitor and a parasitic capacitor coupled  
10          between said bias node and a ground reference point  
11          approaching a unity value such that a biasing voltage at said  
12          biasing node follows said lower supply voltage to minimize  
13          effects of a ground noise signal between the lower supply  
14          voltage and the ground reference point; and

15 forming a buffer output portion on said substrate in communication  
16 with the buffer input portion for producing an output signal.

1 24. (New) The method of claim 23, wherein forming the buffer input portion  
2 further comprises the steps of:

3 forming a first transistor of a first conductivity type on said  
4 substrate;

5 applying the lower supply voltage to a source node of the first  
6 transistor;

7 applying a reference voltage to a gate node of the first transistor;  
8 connecting a drain node of the first transistor to develop as biasing  
9 voltage at said drain node;

10 forming a second transistor of a second conductivity type on said  
11 substrate;

12 connecting a drain node of the second transistor to the drain node  
13 of the first transistor;

14 connecting a gate node of the second transistor to the drain node of  
15 the first transistor for developing the biasing voltage; and

16 connecting a source node of the second transistor to an upper  
17 supply voltage;  
  
18 forming a third transistor of the second conductivity type on said  
19 substrate;  
  
20 connecting a drain node of the third transistor to the drain of a  
21 fourth transistor;  
  
22 connecting a gate node of the third transistor to the drain node of  
23 the first transistor for developing the biasing voltage;  
  
24 connecting a source node of the third transistor to the upper supply  
25 voltage source;  
  
26 forming a fourth transistor of the first conductivity type on said  
27 substrate;  
  
28 connecting a source node of the fourth transistor to the lower  
29 supply voltage;  
  
30 connecting a gate node of the fourth transistor to receive an input  
31 signal externally; and

32 connecting a drain node of the fourth transistor to an input to the  
33 buffer output portion.

1 25. (New) The method of claim 24, wherein the first and fourth transistors are  
2 NMOS transistors, and the second and third transistors are PMOS  
3 transistors.

1 26. (New) The method of claim 24, wherein forming the large capacitor  
2 comprises the step of:

3 connecting said large capacitor between the sources of the first and  
4 fourth transistors of the buffer input portion and the gate of the  
5 second transistor of the buffer input portion.

1 27. (New) The method of claim 24, wherein forming the buffer input portion  
2 further comprises the steps of:

3 connecting the gate of the second transistor to its drain.

1 28. (New) The method of claim 24, wherein forming the buffer input portion  
2 further comprises the steps of:

3 connecting the gate of the second transistor to the gate of the third  
4 transistor.

1 29. (New) The method of claim 24, wherein forming the buffer output portion  
2 which produces output signal comprises the step of:

3 forming a first inverter on said substrate; and

4 connecting an input of said first inverter to the drain of the third  
5 transistor and the drain of the fourth transistor;

1 30. (New) The method of claim 24, wherein the third transistor and the fourth  
2 transistor activate almost simultaneously to minimize the effects of ground  
3 noise on a delay jitter factor of said input buffer.

1 31. (New) The method of claim 23, wherein the large capacitor charge  
2 couples the bias node of the input buffer receiver to the lower supply  
3 voltage of the input buffer receiver and wherein a capacitance value of the  
4 large capacitor is selected by the formula:

$$\frac{CHC}{Cp + CHC} \approx 1$$

6 where:

7 CHC is the capacitance value of the large capacitor,  
8 and

9                   **C<sub>p</sub>** is the capacitance value of the parasitic capacitor.

1       32. (New) The method of claim 23, wherein the capacitance value of the large  
2                   capacitor relative to said parasitic capacitor results in a quicker response  
3                   time for the output signal.

1       33. (New) An apparatus for minimizing effects of ground noise on an input  
2                   buffer receiver comprising:

3                   means for forming a buffer input portion for receiving an input signal  
4                   on a substrate;

5                   means for forming a bias node within said buffer input portion;

6                   means for connecting said a lower supply voltage to said buffer  
7                   input portion;

8                   means for forming a large capacitor between the bias node and the  
9                   lower supply voltage said large capacitor providing a coupling  
10                  ratio between said large capacitor and a parasitic capacitor  
11                  coupled between said bias node and a ground reference point  
12                  approaching a unity value such that a biasing voltage at said  
13                  biasing node follows said lower supply voltage to minimize

14 effects of a ground noise signal between the lower supply  
15 voltage and the ground reference point; and

16 means for forming a buffer output portion on said substrate in  
17 communication with the buffer input portion for producing an  
18 output signal.

1 34. (New) The apparatus of claim 23, wherein forming the buffer input portion  
2 further comprises:

3 means for forming a first transistor of a first conductivity type on  
4 said substrate;

5 means for applying the lower supply voltage to a source node of the  
6 first transistor;

7 means for applying a reference voltage to a gate node of the first  
8 transistor;

9 means for connecting a drain node of the first transistor to develop  
10 as biasing voltage at said drain node;

11 means for forming a second transistor of a second conductivity type  
12 on said substrate;

13 means for connecting a drain node of the second transistor to the  
14 drain node of the first transistor;

15 means for connecting a gate node of the second transistor to the  
16 drain node of the first transistor for developing the biasing  
17 voltage; and

18 means for connecting a source node of the second transistor to an  
19 upper supply voltage;

20 means for forming a third transistor of the second conductivity type  
21 on said substrate;

22 means for connecting a drain node of the third transistor to the  
23 drain of a fourth transistor;

24 means for connecting a gate node of the third transistor to the drain  
25 node of the first transistor for developing the biasing voltage;

26 means for connecting a source node of the third transistor to the  
27 upper supply voltage source;

28 means for forming a fourth transistor of the first conductivity type on  
29 said substrate;

30                   means for connecting a source node of the fourth transistor to the  
31                   lower supply voltage;  
  
32                   means for connecting a gate node of the fourth transistor to receive  
33                   an input signal externally; and  
  
34                   connecting a drain node of the fourth transistor to an input to the  
35                   buffer output portion.

1     35. (New) The apparatus of claim 24, wherein the first and fourth transistors  
2                  are NMOS transistors, and the second and third transistors are PMOS  
3                  transistors.

1     36. (New) The apparatus of claim 24, wherein means for forming the large  
2                  capacitor comprises:

3                   means for connecting said large capacitor between the sources of  
4                  the first and fourth transistors of the buffer input portion and the  
5                  gate of the second transistor of the buffer input portion.

1     37. (New) The apparatus of claim 24, wherein means for forming the buffer  
2                  input portion further comprises:

3                   means for connecting the gate of the second transistor to its drain.

1       38. (New) The apparatus of claim 24, wherein means for forming the buffer  
2              input portion further comprises the steps of:

3                  means for connecting the gate of the second transistor to the gate  
4                  of the third transistor.

1       39. (New) The apparatus of claim 24, wherein means for forming the buffer  
2              output portion which produces output signal comprises:

3                  means for forming a first inverter on said substrate; and

4                  means for connecting an input of said first inverter to the drain of  
5                  the third transistor and the drain of the fourth transistor;

1       40. (New) The apparatus of claim 24, wherein the third transistor and the  
2              fourth transistor activate almost simultaneously to minimize the effects of  
3              ground noise on a delay jitter factor of said input buffer.

1       41. (New) The apparatus of claim 23, wherein the large capacitor charge  
2              couples the bias node of the input buffer receiver to the lower supply  
3              voltage of the input buffer receiver and wherein a capacitance value of the  
4              large capacitor is selected by the formula:

$$\frac{CHC}{Cp + CHC} \approx 1$$

6 where:

7                   **CHC** is the capacitance value of the large capacitor

8                   **CHC**, and

9                   **Cp** is the capacitance value of the parasitic capacitor

10                  **Cp**.

1       42. (New) The apparatus of claim 23, wherein the capacitance value of the  
2                   large capacitor relative to said parasitic capacitor results in a quicker  
3                   response time for the output signal.

### Abstract

[0025] A particular input buffer receiver includes a buffer input portion for receiving an input signal SIGNAL\_IN, a large capacitor capacitance CHC between the PMOS\_a bias node and the VSS source\_lower supply voltage, and a buffer output portion for producing an output signal SIGNAL\_OUT1.  
5 The circuit works to remove ground noise by charge coupling the VB11 bias voltage developed at the bias node to the VSS source\_lower supply voltage of the input device.